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## Elected Board Members

### 2010:

Eric O. Beyne, Steve J. Bezuk, Kitty Pearsall, Eric Perfecto, Ephraim Suhir and C.P. Wong

### 2009:

Philip C.H. Chan, Paul D. Franzon, R. Wayne Johnson, Kwang-Lung Lin, Petri Savolainen, and Leonard W. Schaper

### 2008:

Vasudeva P. Atluri, Li Li, Dongkai Shangguan, Patrick Thompson, Klaus-Jürgen Wolter, and Kishio Yokouchi

## CPMT Society Newsletter

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### TC-Assy - IC and Package Assembly:

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### TC-ECCC - Electrical Contacts, Connectors and Cables:

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### TC-Ed - Education:

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### TC-Test - Electrical Test:

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### TC-Therm - Thermal Management & Thermomech. Design:

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### TC-WLP - Wafer Level Packaging:

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## Strategic Program Directors

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**Global Chapters and Membership:** open

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## Standing Committee Chairs

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**Distinguished Lecturers:** Albert F. Puttlitz, [a.f.puttlitz@ieee.org](mailto:a.f.puttlitz@ieee.org)

**Educational Activities:** Vacant

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**Nominations:** Philip E. Garrou, [pgarrou@rti.com](mailto:pgarrou@rti.com)

## Distinguished Lecturers

**Program Director:** Albert F. Puttlitz

**Lecturers:** Avram Bar-Chen, H. Anthony Chan, Paul Franzon, George Harman, Badih El-Kareh, George Katopis, John H. Lau, Michael Lebby, Michael Pecht, Lue Martens, James E. Morris, T. Paul Parker, Karl Puttlitz, John M. Segelken, Ephraim Suhir, Paul Totta, Walter Trybula, Rao Tummala, Paul Wesling, C.P. Wong, and Ralph W. Wyndrum, Jr.

## Chapters and Student Branches

Refer to [www.cpmt.org](http://www.cpmt.org) for CPMT Society Chapters and Student Branches list

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### 2008 Deadlines for Submitting Articles:

February 25<sup>th</sup>, 2008

May 25<sup>th</sup>, 2008

August 25<sup>th</sup>, 2008

November 25<sup>th</sup>, 2008

Only Articles Sent to [nsltr-input@cpmt.org](mailto:nsltr-input@cpmt.org)  
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